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December 2013



FCP4N60 — N-Channel SuperFET[®] MOSFET

FCP4N60 N-Channel SuperFET[®] MOSFET **600 V, 3.9 A, 1.2** Ω

Features

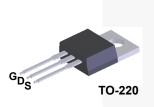
- 650 V @ T_J = 150°C
- Typ. R_{DS(on)} = 1.0 Ω
- Ultra Low Gate Charge (Typ. Q_g = 12.8 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 32 pF)
- 100% Avalanche Tested
- · RoHS Compliant

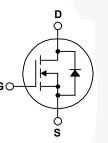
Application

- LCD / LED / PDP TV and Monitor Lighting
- Solar Inverter
- AC-DC Power Supply

Description

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter	FCP4N60	Unit	
V _{DSS}	Drain-Source Voltage	600	V	
I _D	Drain Current - Continuous ($T_C = 25^{\circ}C$) - Continuous ($T_C = 100^{\circ}C$)		3.9 2.5	A A
I _{DM}	Drain Current - Pulsed	(Note 1)	11.7	A
V _{GSS}	Gate-Source voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	128	mJ
I _{AR}	Avalanche Current	(Note 1)	3.9	A
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P _D	Power Dissipation $(T_C = 25^{\circ}C)$ - Derate Above $25^{\circ}C$		50 0.4	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
Τ _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.		300	°C

Thermal Characteristics

Symbol	Parameter	FCP4N60	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.5	°C/W	
	Thermal Resistance, Junction to Ambient, Max.	83	C/W	
R _{θJA}			1	

FCP4N60
N-Channel
SuperFET®
MOSFET

		Top Mark	Package	ckage Packing Method Reel Size		Та	ape Width	Qu	Quantity 50 units	
		FCP4N60	TO-220	Tube	N/A		N/A			
Electric	al Char	racteristics T _C = 25	5ºC unless oth	nerwise noted.						
Symbol		Parameter		Conditions		Min.	Тур.	Max.	Unit	
Off Chara	cteristics									
BV _{DSS}	Drain-Source Breakdown Voltage		$V_{GS} =$	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}, \text{ T}_{J} = 25^{\circ}\text{C}$		600			V	
			$V_{GS} =$	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}, \text{ T}_{J} = 150^{\circ}\text{C}$			650		V	
ΔBV_{DSS} / ΔT_{J}	Breakdow Coefficien	vn Voltage Temperature t	I _D = 25	$I_D = 250 \ \mu\text{A}$, Referenced to 25°C			0.6		V/°C	
BV _{DS}	Drain-Sou Voltage	urce Avalanche Breakdow	/n V _{GS} =	V _{GS} = 0 V, I _D = 3.9 A			700		V	
I _{DSS}	Zero Gate	e Voltage Drain Current		$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$				1 10	μΑ μΑ	
I _{GSSF}	Gate-Bod	y Leakage Current, Forw	ard V _{GS} =	$V_{GS} = 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$				100	nA	
I _{GSSR}	Gate-Bod	y Leakage Current, Reve	rse V _{GS} =	-30 V, V _{DS} = 0 V				-100	nA	
On Charao	cteristics									
V _{GS(th)}	Gate Thre	eshold Voltage	$V_{DS} =$	V _{GS} , I _D = 250 μA		3.0		5.0	V	
R _{DS(on)}	Static Dra On-Resist	in-Source tance	V _{GS} =	V_{GS} = 10 V, I _D = 2.0 A			1.0	1.2	Ω	
9 _{FS}	Forward 1	Fransconductance	$V_{DS} =$	40 V, I _D = 2.0 A			3.2		S	
Dynamic (Characteris	tics								
C _{iss}	Input Cap	acitance		$V_{DS} = 25 V, V_{GS} = 0 V,$			415	540	pF	
C _{oss}	Output Ca	apacitance	f = 1.0	MHz			210	275	pF	
C _{rss}	Reverse 7	Fransfer Capacitance					19.5		pF	
C _{oss}	Output Ca	apacitance	$V_{DS} =$	480 V, $V_{GS} = 0$ V, f =	1.0 MHz		12	16	pF	
C _{oss} eff.	Effective	Output Capacitance	$V_{DS} =$	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$			32		pF	
Switching	Characteri	stics								
t _{d(on)}	Turn-On [Delay Time		$V_{DD} = 300 \text{ V}, \text{ I}_D = 3.9 \text{ A}$ $R_G = 25 \Omega$		-	16	45	ns	
t _r	Turn-On F	Rise Time	$R_{G} = 2$				45	100	ns	
t _{d(off)}	Turn-Off	Delay Time					36	85	ns	
t _f	Turn-Off F	Fall Time			(Note 4)		30	70	ns	
Qg	Total Gate	e Charge		$V_{DS} = 480 \text{ V}, \text{ I}_{D} = 3.9 \text{ A}$			12.8	16.6	nC	
Q _{gs}	Gate-Sou	rce Charge	V _{GS} =	10 V			2.4		nC	
Q _{gd}	Gate-Drai	n Charge			(Note 4)		7.1		nC	
Drain-Sou	rce Diode (Characteristics and Max	imum Rating	s				/ F		
I _S	Maximum Continuous Drain-Source Diode Forward Current					3.9	Α			
I _{SM}	Maximum	Pulsed Drain-Source Dic	ode Forward C	Current				11.7	Α	
V_{SD}	Drain-Sou	urce Diode Forward Voltag		0 V, I _S = 3.9 A				1.4	V	
t _{rr}	Reverse F	Recovery Time		$V_{GS} = 0 V, I_{S} = 3.9 A$			277		ns	
Q _{rr}	Reverse F	Recovery Charge	dl _F /dt =	=100 A/μs			2.07		μC	

Notes:

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. I_{AS} = 1.9 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C.

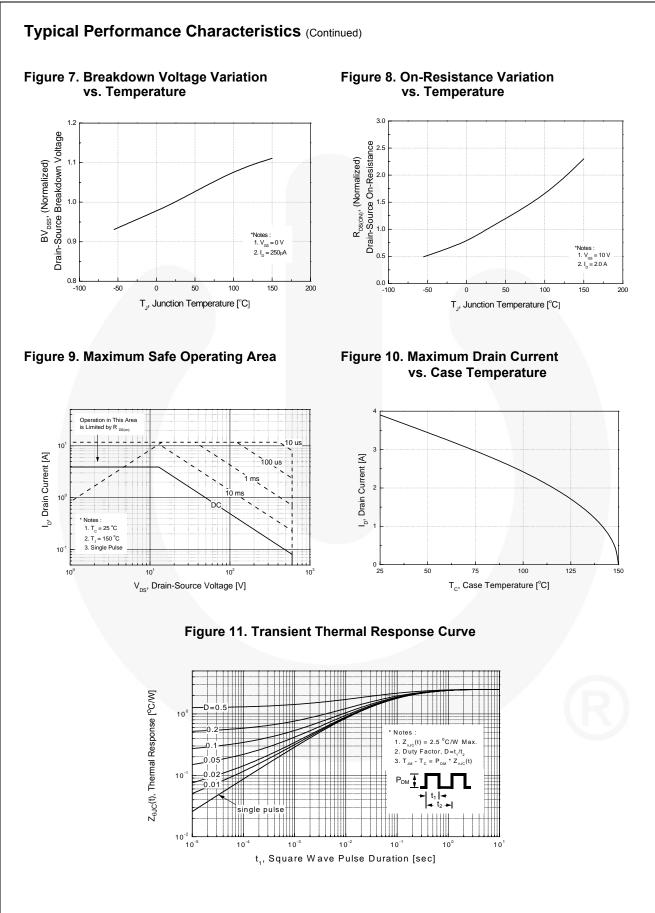
3. I_{SD} \leq 3.9 A, di/dt \leq 200 A/µs, V_{DD} \leq BV_{DSS}, starting T_J = 25°C.

4. Essentially independent of operating temperature typical characteristics.

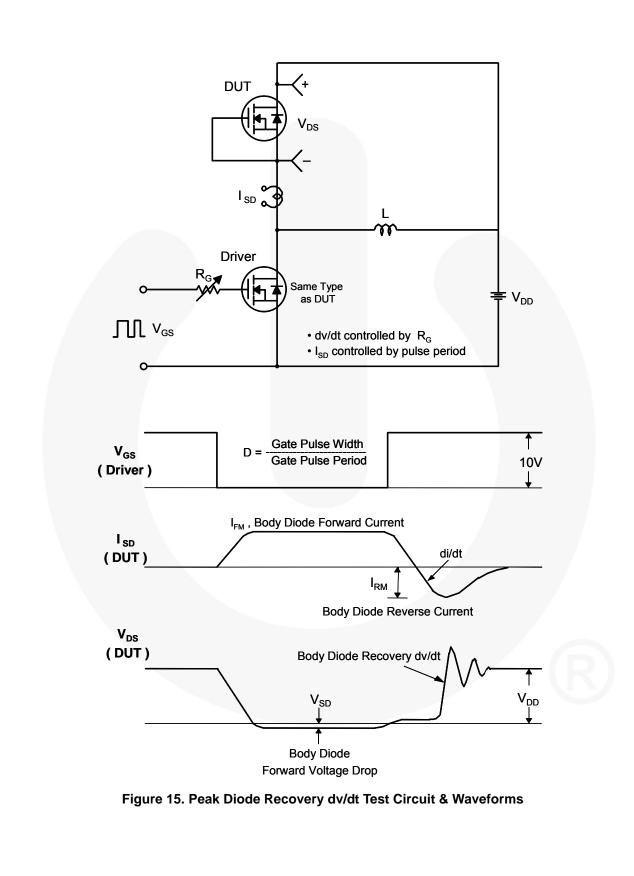
Typical Performance Characteristics Figure 1. On-Region Characteristics Figure 2. Transfer Characteristics V_{GS} 15.0 V 10.0 V 8.0V 7.5 V 7.0 V 6.5 V 6.0 V 10 10¹ Тор ₹ I_D, Drain Current [A] I_b, Drain Current 150°C 5.5 V Bottom 10⁰ 25°C -55°C Notes : 1. 250µs Pulse Test * Note 1. V_{DS} = 40V 2. 250µs Pulse Test 2. T_c = 25^oC 0.1 10⁻¹ 0.1 10 2 4 6 8 10 V_{DS}, Drain-Source Voltage [V] $\rm V_{_{GS}}$, Gate-Source Voltage $\,[V]$ Figure 3. On-Resistance Variation vs. Figure 4. Body Diode Forward Voltage **Drain Current and Gate Voltage** Variation vs. Source Current and Temperatue [0], Drain-Source On-Resistance 10 ₹ **Reverse Drain Current** $V_{GS} = 10V$ 10 150°C = 201/ 25°C BR, R_{DS(ON)} I Notes : 1. V_{GS} = 0V * Note : T = 25°C 2. 250µs Pulse Test 0.0 10 2.5 5.0 7.5 10.0 12.5 0.2 0.4 0.6 0.8 1.0 1.2 I_D, Drain Current [A] V_{SD}, Source-Drain Voltage [V] **Figure 5. Capacitance Characteristics Figure 6. Gate Charge Characteristics** 1200 12 $$\begin{split} \mathbf{C}_{_{\mathrm{iss}}} &= \mathbf{C}_{_{\mathrm{gs}}} + \mathbf{C}_{_{\mathrm{gd}}} \left(\mathbf{C}_{_{\mathrm{ds}}} = \text{shorted} \right) \\ \mathbf{C}_{_{\mathrm{oss}}} &= \mathbf{C}_{_{\mathrm{ds}}} + \mathbf{C}_{_{\mathrm{gd}}} \end{split}$$ V_{DS} = 120V V_{DS} = 300V 1000 10 V_{GS}, Gate-Source Voltage [V] V_{DS} = 480V 800 ۶ Capacitance [pF] Notes : 1. V_{gs} = 0 V 2. f = 1 MHz 600 400 200 2 * Note : I_D = 3.9A 0 L 10⁶ 0 k 0 . . . 10 10 15 V_{DS}, Drain-Source Voltage [V] Q_G, Total Gate Charge [nC]

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 V_{GS} Same Type as DUT 50KQ Q_g 12\ 300nF F V_{DS} \mathbf{Q}_{gd} Q_{gs} DUT I_G = const. Charge Figure 12. Gate Charge Test Circuit & Waveform R VDS VDS 90% V_{DD} R_{G} 10% V_{GS} DUT V_{GS} ∏ 0 Figure 13. Resistive Switching Test Circuit & Waveforms BV_{DSS} BV_{DSS} - V_{DD} L $E_{AS} = \frac{1}{2} L I_{AS}^2$ V_{DS} $\mathsf{BV}_{\mathsf{DSS}}$ I_D 0 I_{AS} R_{G} VDD I_D (t) V_{GS} $V_{DS}(t)$ DUT V_{DD} Time t_n Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





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